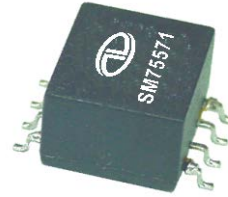


TELECOM MAGNETICS SM75571



Features

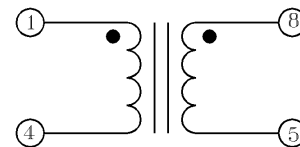
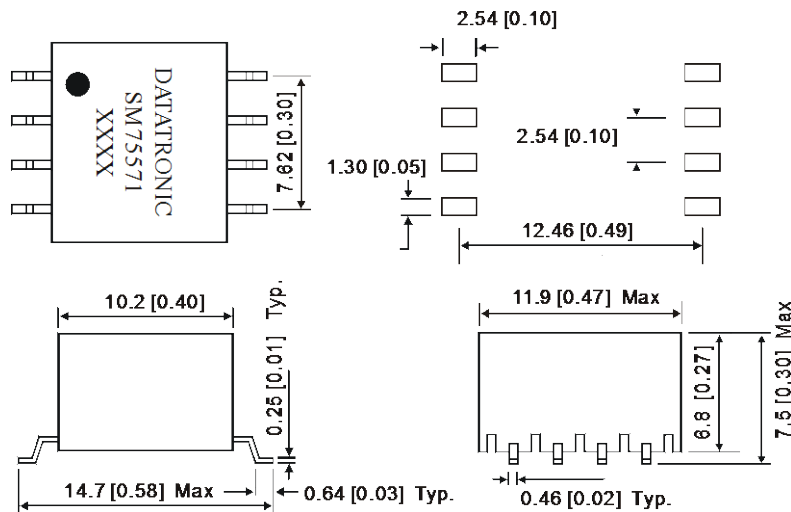
- Designed for use Conexant SMART HCF FFI Chipset
- SMT package



ELECTRICAL SPECIFICATIONS AT 25°C

URNS RATIO (1-4) : (5-8)	1 : 2±2%
OCL @100kHz, 1V (1-4)	40μH MIN
LEAKAGE INDUCTANCE @4MHz, 1V	7μH MAX
INTERWINDING CAPACITANCE @1MHz	10pF MAX
DCR (1-4)	0.2Ω MAX
DCR (5-8)	0.4Ω MAX
HIPOT PRIMARY & SECONDARY 1 MINUTE	1500VRMS

OUTLINE DIMENSIONS



SCHEMATIC

Notes:

- All dimensions are in inches and typical unless otherwise specified.
- Coplanarity: ±.004
- For non-RoHS parts replace SM prefix with 42- (e.g. SM75571 becomes 42-75571)
- Terminal finish is compliant to RoHS requirements. Solder in accordance with J-STD-020C